Amendment under 37 CFR 1.111
Hiroshi ANDO et al.

U.S. Patent Application Serial No. 09:701,011 Attorney Docket No. 001550

Table 1					-		
				ventive	Inventive Example	1	,
		-	2	3	4	ç	۵
	Curing agent (solution B)						
+ 40 Co. 10	Tin octulate	3	3	3	3	3	3
Divalent		0.3	0.3	0.3	0.3	0.3	0.3
tin catalyst	Lauryiamine						
Tetravalent tin	Dibutyltin dilaurate						
catalyst					,	,	
Amino-containing	N-{β-aminoethyl}-γ-aminopropyltrimethoxysilane	7	7	7	7	7	7
silane compound							
Octobration and and	Vinvitrimethoxysilane	0.2	0.2	0.2	0.2	0.2	0.2
Denyaraning agent	Dolymproviene glycol (average molecular weight = 3,000)	6.5				6.5	
Plasticizer	Description process of the control o		6.5			_	6.5
	Parallili Daseu plasticizet (Exxsol 5.100)			6.5			
	Polyoxyalkylene Having Teachive Sincol group				6.5		
	Allyl ether gloup-refinition polycydamyrana						
	Ulisodecyi phthalate	5	20	20	20	20	20
Filler	Precipitated calcium carbonate	0.7	07	22	27	3	
	Base resin (solution A)						
Curable organic	Polyoxyalkylene having reactive silicon group in the molecule	100	100	93.5	100	100	
based polymer (d)	Polyisobutylene having reactive silicon group in the molecule						100
Epoxy-containing	y-Glycidoxypropyltrimethoxysilane	7	7	7	2	7	7
silane compound					,	,	,
Epoxy resin	Bisphenol A-epichlorohydrin type epoxy resin	-	-	-	_	_	-
Lpon) toods							

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				=	nventive	Inventive Example	41	
		-	1	2	3	4	5	9
Mixing ratio *	Weight ratio (base resin:curing agent)		100:10	100:10 100:10	100:10	100:10	100:10	100:10
Mixing ability **	Easiness for weighing and mixing		+	+	+	+	+	+
Storage stability	Initial (Refore 50°C × 4 weeks store)	Ηr	9	9	9	9	9	9
(surface curing time)	After 50°C x 4 weeks	ī	9	9	9	6	9	9
Adhesiveness after	Substrate: plate glass	break mode	++	++	++	+	‡	‡
storage of curing	Substrate: aluminum alloy (anodic oxidation)	break mode	++	‡	+	++	++	+
agent (water		break mode	+	+	+	‡	+	+
resistance)								
Elastic Recovery	23°C, 100% elongation 24 hr. set, 1 hr after release	*** %	94%	95%	94%	94%	95%	%56

*:Base resin/curing agent mixing ratio **: Base resin/curing agent mixing ability

***: Elastic recovery ratio

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Please amend Table 2, pages 58-59 as follows:

Table 2								
				ompar	Comparative Example	ample		
		+	2	က	4	5	9	7
	Curing agent (solution B)							
Rivalent	Tin octylate	£	က	5	5		2	S
tin catalyst	Laurylamine	0.3	0.3	4.0	0.4		0.4	0.4
Tetravalent tin	Dibutyltin dilaurate				-	'n		
catalyst								
Amino-containing	N-(β-aminoethyl)-γ-	7		7	7	7	7	7
silane compound	aminopropyltrimethoxysilane							
Dehydrating agent	Vinyltrimethoxysilane	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Plasticizer	Polypropylene glycol (average molecular		6.5			6.5	6.5	6.5
	weight = 3,000)							
	Paraffin based plasticizer (Exxsol D-130)							
	Polyoxyalkylene having reactive silicon					•		_
	group in the molecule							
	Allyl ether group-terminus polyoxyalkylene	:						
	Diisodecyl phthalate	6.5						
Filler	Precipitated calcium carbonate	20	20		20	20	20	20
	Base resin (solution A)							
Curable organic	Polyoxyalkylene having reactive silicon	100	100	100	100	100	100	100
based polymer (d)	group in the molecule							
	Polyisobutylene having reactive silicon							
	group in the molecule							
Epoxy-containing	y-Glycidoxypropyltrimethoxysilane	7	7	7	7	7	7	
silane compound								
Epoxy resin	Bisphenol A-epichlorohydrin type epoxy	~	-	-	-	₹-		_
	resin							
								1

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		1			Compa	Comparative Example	xample		
			-	2	c	4	5	g	7
Veight ratio (Weight ratio (base resin:curing agent)	agent)	100:10	100:10	100:10 100:10 100:2.5	100:8	100:10		100:10 100:10
Easiness for weig	eighing and mixing	ng	+	+	+		+	+	+
Initial (R	Initial (Refore 50 C x 4 veeks store	veeks store	5	9	9	Z Z	S	9	9
After 50°C x 4 weeks store	eeks store	Hr	30	9	9	Z.	5	9	9
Substrate: plate g	glass	break mode	+	ı		Z Z	‡	+	+
Substrate: aluminum alloy	num alloy	break mode	+			Σ	++	+	+
anodic oxidation)	(u								
Substrate: mortar	ar slabs	break mode			•	Σ	+		•
23°C, 100% elongation 24 hr.	gation 24 hr.	*** %	95%	%56	85%	Σ z	55%	95%	93%
set, 1 hr after release	lease			_					

(Continued)

*:Base resin/curing agent mixing ratio

**: Base resin/curing agent mixing ability

***: Elastic recovery ratio

N. D.: not detectable, N. M.: not measurable